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PATENT

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RECORDING COVER SHEET

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1. Assignor: Yeong-Chih Lai
2. Assignee: UNITED MICROELECTRONICS CORP.
No.3, Li-Hsin Road 2,
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3. Nature of Conveyance: Assignment of patent
4. Reference number: Application filed herewith.

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6. Number of applications affected by this recording: 1

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I declare under penalty of perjury that to the best of my knowledge and belief, the information contained on this cover sheet is true and correct, and that any copy submitted herewith is a true and correct copy of the original document.

Date:

4/14/1999

Winston Hsu

Winston Hsu
U.S. Patent Agent
Reg. No.: 41,526

ASSIGNMENT OF INVENTION

I, (Assignor Name) Yeong-Chih Lai, residing at (Address) No.16, Lane 2, Cheng-Kung 3rd Rd., Nan-Tou City, Nan-Tou Hsien, Taiwan, R.O.C., have invented a device called "Method of forming a spacer of a gate on a semiconductor wafer"

(Assignee name) UNITED MICROELECTRONICS CORP., (hereinafter "Assignee"), of (Assignee address) No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu, Taiwan, R.O.C., wishes to acquire the entire right, title, and interest in and to the invention and to any letters patent that may be granted therefor in the United States and in any and all foreign countries.

Accordingly, in consideration of the sum of One Dollar, (\$1.00) to me in hand paid, the receipt of which is hereby acknowledged, and other good and valuable consideration, Assignor, hereby sells, assigns, and transfers to Assignee the full and exclusive right to the above described invention in the United States and its territorial possessions, and in all foreign countries. The rights granted include the entire right, title, and interest in and to any and all letters patent which may be granted on the invention, including any rights gained by divisions, reissues, continuations, and extensions of the above described application.

I hereby authorize and request the Patent and Trademark Office Officials in the United States and any and all foreign countries to issue any and all letters patent, when issued, to Assignee, as the assignee of my entire right, title, and interest in and to the invention, for the sole use and enjoyment of Assignee and its successors and assignees.

Further, I agree that I will communicate to Assignee or its representatives any facts known to me respecting the invention, to testify in any legal proceedings, to sign all lawful papers, to execute all divisions, continuations, substitutions, renewal and reissue applications, and to generally do those things necessary to aid Assignee and its successors and assigns to obtain and enforce proper protection for the invention in the United States and in any and all foreign countries.

Date: 04.10.1989,

Yeong-Chih Lai (Assignor signature)

Yeong-Chih Lai (Print Assignor's name)